



Materials Declaration Form

IPC	1752	Version	2
Form Type *	Distribute		
Sectionals *	Material Info Manufacturing Info	Subsectionals *	A-D

** : Required Field*

Supplier Information			
Company Name *	STMicroelectronics	Response Date *	2020-05-05
Company Unique ID	NL 008751171B01		
Contact Name *	Refer to Supplier Comment section		Refer to Supplier Comment section
Contact Phone *	Refer to Supplier Comment section	Contact Email *	Refer to Supplier Comment section
Authorized Representative *	giovanni giacopello	Representative Title	ADG MD CHAMPION
Representative Phone *	Refer to Supplier Comment section	Representative Email *	Refer to Supplier Comment section
Supplier Comment	Online Technical Support - STMicroelectronics : http://www.st.com/web/en/support/support.html		

Uncertainty Statement

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Legal Statement

Supplier Acceptance *	true	Legal Declaration *	Standard
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Legal Statement

Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form.

Product				
Mfr Item Number	Mfr Item Name	Version	Mfr Site	Date
TDA7564B	H84W*UK28DB6	A	3068	2020-05-05
	Amount	UoM	Unit type	ST ECOPACK Grade
	7099	mg	Each	ECOPACK 2
Comment	ECOPACK® 2 is STMicroelectronics trade name for ROHS compliant device without Brominated and Chlorinated compound (900ppm) and without Antimony oxide flame retardant (in each organic material)			

Manufacturing information				
J-STD-020 MSL Rating	Classification Temp	Nbr of Reflow Cycles		
Not Applicable	Not Applicable	3		
Bulk Solder Termination	Terminal Plating	Terminal Base Alloy	Comment	
Not Applicable	Tin (Sn), matte, annealed	Copper Alloy	CD00243405	



Package Designator	Size	Nbr of instances	Shape	
ZIP	29.00,15.50,5.00	25	Through hole	
Comment	FLEXIWATT 25 LEADS FULLMOLD #2			

QueryList : RoHS Directive 2011/65/EU-July 2011 – Annex II amended by Directive 2015/863-March 2015	
Query	Response
1 - Product(s) meets EU RoHS requirement without any exemptions	FALSE
2 - Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)	FALSE
3 - Product(s) meets EU RoHS requirements by application of the selected exemption(s)	TRUE
4 - Product(s) does not meet EU RoHS requirements and is not under exemptions	FALSE
Exemption Id.	Description
7a	Lead in high melting temperature type solders (i.e. lead- based alloys containing 85 % by weight or more lead)

QueryList : ELV directive : 2000/53/EC amended 2017/2096 _November 2017	
Query	Response
1 - Product(s) meets EU ELV requirements without any exemptions	FALSE
2 - Product(s) meets EU RoHS requirements by application of the selected exemption(s)	TRUE
Exemption Id.	Description
8e	Lead in high melting temperature type solders (i.e. lead-based alloys containing 85 % by weight or more lead)

QueryList : California Prop65 list, dated 3rd January 2020			
Query			Response
1 - The product does not contain identified substance from California Prop 65 List, no exposure to consumers is foreseen			FALSE
2 - The product is containing below substance(s) from California Prop 65 List, no exposure to consumers is foreseen			TRUE
Substance	amount in product (mg)	Application	ppm in product
Nickel	0.13	die	18
Lead	10.45	soft solder	1472

QueryList : REACH-16th January 2020				
Query				Response
1 - Product(s) does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH				FALSE
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product
Lead	1000 ppm	10.45	Soft solder	1472
2 - Product(s) does not contain REACH Substances Of Very High Concern in any Embedded article nor Homogeneous Material above the limits per the definition within REACH				FALSE
CategoryLevel_Name	CategoryLevel_Threshold	Amount in Embedded Article / Homogeneous Material (mg)	Application - Article / Homogeneous Material	ppm in Article /Homogeneous Material
Lead	1000 ppm	10.45	Soft solder	974995

Material Composition Declaration :						Mfr Item Name	H84W*UK28DB6					
note : Substance present with less 0.001mg will not be declared in this document												
Homogeneous Material	Material Group	Mass	UoM	Level	Substance Category	Substance	CAS	Exempt	Mass	UoM	Concentration in homogeneous material (ppm)	Concentration in product (ppm)
Die	M-011 Other inorganic materials	26.796	mg	supplier	die	Silicon(Si)	7440-21-3		25.530	mg	952754	3596
				supplier	metallisation	Aluminium(Al)	7429-90-5		0.168	mg	6270	24
				supplier	metallisation	Chromium(Cr)	7440-47-3		0.015	mg	561	2
				supplier	metallisation	Gold(Au)	7440-57-5		0.039	mg	1455	5
				supplier	metallisation	Nickel(Ni)	7440-02-0		0.130	mg	4851	18
				supplier	metallisation	Tungsten(W)	7440-33-7		0.266	mg	9927	37
				supplier	Passivation	Silicon nitride(SiN)	12033-89-5		0.041	mg	1530	6
				supplier	passivation	Silicon oxide	7631-86-9		0.409	mg	15263	58
				supplier	polymer coating	PIX1 Gamma-butyrolactone	96-48-0		0.198	mg	7389	28
				Leadframe	M-004 Copper and its alloys	5221.405	mg	supplier	alloy & coating	Copper(Cu)	7440-50-8	
supplier	alloy & coating	Iron(Fe)	7439-89-6						2.402	mg	460	338
supplier	alloy & coating	Iron Phosphide(FeP)	26508-33-8						4.386	mg	840	618
Soft solder	Solder	10.718	mg	SVHC	solder	Lead(Pb)	7439-92-1	7a-Lead in high melting temper	10.450	mg	974995	1472
				supplier	solder	Silver(Ag)	7440-22-4		0.161	mg	15021	23
				supplier	solder	Tin(Sn)	7440-31-5		0.107	mg	9984	14
Bonding wires	M-004 Copper and its alloys	2.059	mg	supplier	wire	Copper(Cu)	7440-50-8		2.059	mg	1000000	290
Encapsulation	M-011 Other inorganic materials	1814.079	mg	supplier	mold compound	Amorphous silica	7631-86-9		1541.967	mg	850000	217197
				supplier	mold compound	Epoxy Cresol Novolac	29690-82-2		108.845	mg	60000	15332
				supplier	mold compound	Phenol type resin	proprietary		72.563	mg	40000	10221
				supplier	mold compound	Mercaptopropyl trimethoxysilane	4420-74-0		5.442	mg	3000	767
				supplier	mold compound	Other	proprietary		67.121	mg	37000	9454
				supplier	mold compound	Carbon black	1333-86-4		12.699	mg	7000	1789
connections coating	Solder	24.343	mg	supplier	mold compound	Bismuth (Bi)	7440-69-9		5.442	mg	3000	767
				supplier	solder alloy	Tin (Sn)	7440-31-5		24.343	mg	1000000	3429